

ABSTRACT

A sputtering apparatus includes a space defining member defining a sputtering space for forming a film on a substrate. The space defining member includes a concave portion, and an opening portion is provided in
5 the bottom portion of the concave portion. The sputtering apparatus includes a shield member configured to shield the opening portion from the sputtering space. The opening portion is formed so that a pressure gauge capable of measuring the pressure
10 in the sputtering space can be attached, and the shield member is arranged so that at least a part of the shield member is buried in the concave portion.